SHARP PC457L0NIP

# PC457L0NIP

### **■** Features

1. High resistance to noise (CMR:MIN. 15kV/µs)

2. High speed response

 $(t_{PHL}: MAX. 0.8 \mu s, t_{PLH}: MAX. 0.8 \mu s)$ 

3. Mini-flat package

4. Isolation voltage (V<sub>iso (rms)</sub>: 3.75kV)

5. Recognized by UL, file No. E64380 (Model No.PC457L)

## ■ Applications

1. Programmable controller

2. Inverter

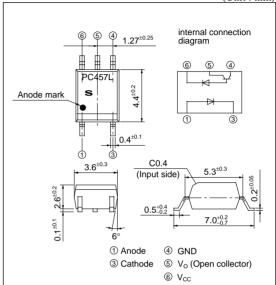
<b>Absolute Maximum Ratings</b> $(T_a=25^{\circ}C)$								
Parameter		Symbol	Rating	Unit				
Input	*1 Forward current	$I_{\mathrm{F}}$	25	mA				
	Reverse voltage	$V_R$	5	V				
	*2 Power dissipation	P	45	mW				
Output	Supply voltage	$V_{CC}$	-0.5 to +30	V				
	Output voltage	$V_{\rm o}$	-0.5 to +20	V				
	Output current	$I_{O}$	8	mA				
	*3 Power dissipation	Po	100	mW				
*3 Total power dissipation		$P_{tot}$	100	mW				
*4 Isolation voltage		$V_{iso\;(rms)}$	3.75	kV				
Operating temperature		$T_{opr}$	-55 to +100	°C				
Storage temperature		$T_{stg}$	-55 to +125	°C				
*5 Soldering temperature		$T_{sol}$	270	°C				

<sup>\*1</sup> When ambient temperature goes above 70°C, the power dissipation goes down at  $0.8 \text{mA}/^{\circ}\text{C}$ 

# High Speed and High CMR \*OPIC Photocoupler

**■** Outline Dimensions

(Unit: mm)



<sup>\* &</sup>quot;OPIC" (Optical IC) is a trademark of the SHARP Corporation.

An OPIC consists of a light-detecting element and signalprocessing circuit integrated onto a single chip.

<sup>\*2</sup> When ambient temperature goes above 70°C, the power dissipation goes down at  $0.8 mW/^{\circ}C$ 

<sup>\*3</sup> When ambient temperature goes above 70°C, the power dissipation goes down at 1.8mW/°C

<sup>\*4 40</sup> to 60%RH, AC for 1minute

<sup>\*5</sup> For 10s

■ Electro-optical Characteristics (T <sub>a</sub> =25°C										
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit			
	Forward voltage	$V_{\rm F}$	I <sub>F</sub> =16mA	-	1.7	1.95	V			
Input	Reverse current	$I_R$	V <sub>R</sub> =5V	_	_	10	μΑ			
	Terminal capacitance	$C_t$	V <sub>F</sub> =0V, f=1MHz	_	60	250	pF			
Output	High level output current (1)	I <sub>OH (1)</sub>	$I_F=0, V_{CC}=5.5V, V_O=5.5V$	_	3	500	nA			
	High level output current (2)	I <sub>OH (2)</sub>	$I_F=0, V_{CC}=15V, V_O=15V$	-	_	1.0	μΑ			
	*6 High level output current (3)	I <sub>OH (3)</sub>	$I_F=0, V_{CC}=15V, V_O=15V$	_	_	50	μΑ			
	High level supply current (1)	I <sub>CCH (1)</sub>	$I_F=0$ , $V_{CC}=15V$ , $V_O=open$	-	0.02	1.0	μА			
	*6 High level supply current (2)	I <sub>CCH (2)</sub>	I <sub>F</sub> =0, V <sub>CC</sub> =15V, V <sub>O</sub> =open	_	_	2.0	μΑ			
	Low level supply current	$I_{CCL}$	I <sub>F</sub> =16mA, V <sub>CC</sub> =15V, V <sub>O</sub> =open	_	120	_	μΑ			
	Low level output voltage	$V_{OL}$	I <sub>F</sub> =16mA, V <sub>CC</sub> =4.5V, I <sub>O</sub> =2.4mA	_	_	0.4	V			
Transfer charac- teristics	Current transfer ratio (1)	CTR (1)	I <sub>F</sub> =16mA, V <sub>CC</sub> =4.5V, V <sub>O</sub> =0.4V	19	_	50	%			
	*6 Current transfer ratio (2)	CTR (2)	$I_F=16mA, V_{CC}=4.5V, V_O=0.4V$	15	_	_	%			
	*7 "High→Low" propagation delay time	$t_{PHL}$	$I_F=16mA$ , $V_{CC}=5V$	_	0.2	0.8	μs			
	*7 "Low→High" propagation delay time	$t_{PLH}$	$R_L=1.9\Omega$	_	0.6	0.8	μs			
	*8 Instantaneous common mode rejection voltage "Output : High level"	СМн	$\begin{array}{c} I_{F}\!\!=\!\!0,R_{L}\!\!=\!\!1.9k\Omega \\ V_{CC}\!\!=\!\!5V,V_{CM}\!\!=\!\!1.0kV_{(p\text{-}p)} \end{array}$	15	30	_	kV/μs			
	*8 Instantaneous common mode rejection voltage "Output : Low level"	$CM_L$	$\begin{array}{c} I_{F}\!\!=\!\!16mA,R_{L}\!\!=\!\!1.9k\Omega \\ V_{CC}\!\!=\!\!5V,V_{CM}\!\!=\!\!1.0kV_{(P\!-\!P)} \end{array}$	-15	-30	_	kV/μs			
	Isolation resistance	R <sub>ISO</sub>	DC=500V, 40 to 60%RH	5×10 <sup>10</sup>	1×10 <sup>11</sup>	_	Ω			
	Floating capacitance	$C_{\rm f}$	V=0, f=1MHz	_	0.6	1.0	pF			

<sup>\*6</sup> T<sub>a</sub>=0 to 70°C

Fig.1 Test Circuit for Propagation Delay Time

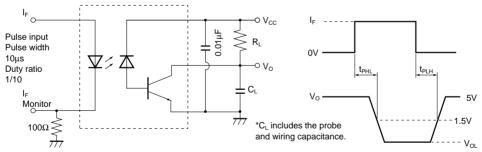
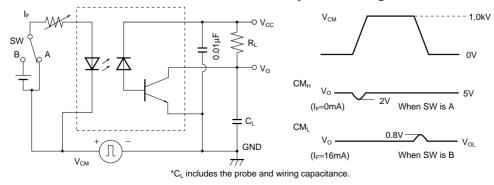


Fig.2 Test Circuit for Instantaneous Common Mode Rejection Voltage



<sup>\*7</sup> Refer to Fig.1 \*8 Refer to Fig.2

Fig.3 Forward Current vs. Ambient Temperature

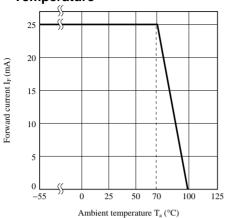


Fig.5 Forward Current vs. Forward Voltage

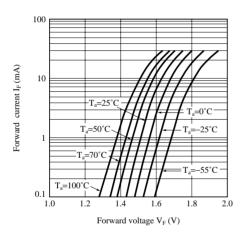


Fig.7 Output Current vs. Output Voltage

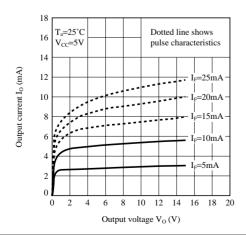


Fig.4 Power Dissipation vs. Ambient Temperature

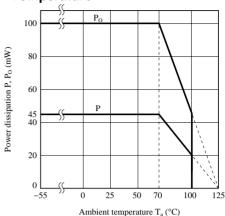


Fig.6 Relative Current Transfer Ratio vs. Forward Current

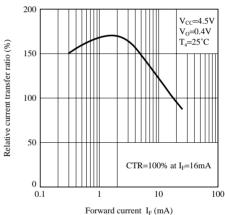
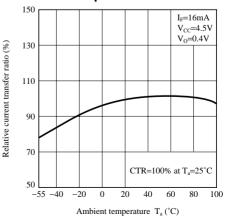


Fig.8 Relative Current Transfer Ratio vs. Ambient Temperature



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Fig.9 High Level Output Current vs. Ambient Temperature

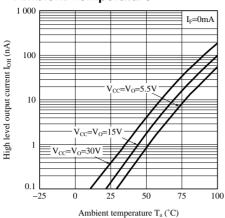
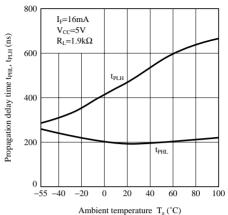


Fig.10 Propagation Delay Time vs. Ambient Temperature



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